

■ Typical Specifications

Ito	ms	Specifications			
Tie		Standard	Medium-current		
Rating (max.)/(mi (Resistive load)	n.)	0.1A 30V DC 50μA 3V DC	1 A 25V DC		
Contact resistanc (Initial /After opera	-	20mΩ max. / 40mΩ max.			
Operating forces	2-pole	2±1N	3±1.5N		
Operating forces	4-pole	2.5±1N	4±2N		
Operating life	Without load	30,000 cycles	10,000 cycles		
Operating line	With load	10,000 cycles (0.1A 30V DC)	5,000 cycles (1A 25V DC)		

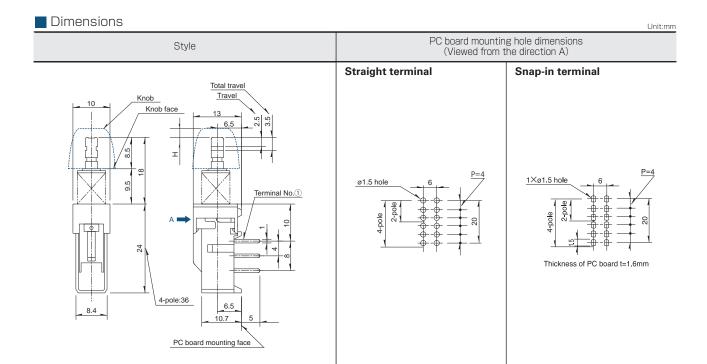
Product Line

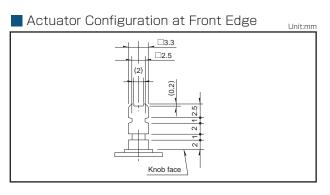
Changeover	Travel (mm)	Total travel	Rating	Mounting method	Poles	Operation Terminal		I Uperation I .			Product No.
timing	(111111)	(mm)		metriou			type	Japan	Export		
				Standard PC board Medium- current	2 -PC board 4	Latching -	Straight		1,250	SPUN191400	
							Snap-in	250		SPUN191600	
			Standard			Momentary ·	Straight			SPUN190900	
	2.5	2.5 3.5 Me	Stariuaru				Snap-in			SPUN191000	
Non shorting						4	Straight	140	700	SPUN194700	
							Snap-in	1	700	SPUN194900	
					2	2 Latching	Straight	250	1.250	SPUN192600	
							Snap-in	230	1,230	SPUN192800	
					4		JIIαμ-III	140	700	SPUN19C400	

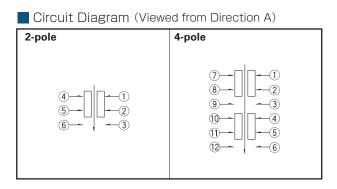
Packing Specifications

Bulk

Product No.	Number of pa	Export package		
Floudet No.	1 case / Japan	1 case / export packing	measurements (mm)	
SPUN190900, SPUN191000 SPUN191400, SPUN191600 SPUN192600, SPUN192800	250	1,250	400×270×290	
SPUN194700, SPUN194900 SPUN19C400	140	700	,	



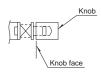




■ Knob Lineup							
Knob outline drawing	Model	Knob attachment height (H)					
Square knob 11.9 12.3 7 12.3 7 12.3	Color:Black	UE201011	2				
Round knob	Color:Black	UE200011	6				

Notes

We recommend the use of adhesive to secure the knob when mounting onto switches.



					Horizontal			
	Series		SPPJ3	SPPJ2	SPUJ	SPUN	SPUN medium current	
	Photo			M A				
W		5 or 6.6	7.2	7.5	,	10		
Dimensio (mm)	ins	D	1	2	15.2 22.7	24 36		
	Н		8.3	9.6	8.8	13		
Tra	vel (mm)		2	.5	2	2	2.5	
Total -	travel (m	m)	3	.5	3	3	3.5	
Numb	er of pole	es	1 2	2		2 4		
	perating rature rar	nge	-40℃ to +85℃		-10°C to +60°C			
Autor	motive us	se	•	•	_	_	_	
Lit	fe cycle		★ 3	*3	★3	*3	*3	
Rati (Resi	ng (max.) stive load	d)	0.2A 3	BOV DC	0.1A 30V DC 1A 25V			
Rati (Resi	ng (min.) stive load	d)		50μΑ				
Durability	Operat withou	ing life It load	10),000 cycles 40mΩ ma	ax. 30,000 cycles 10,000 cyc 40mΩ max. 40mΩ ma			
Durability	Operating li (at max. r			$10{,}000$ cycles $40m\Omega$ max.				
	Initial c resist	ontact tance			20mΩ max.			
Electrical performance	Insul resist	ation tance	100MΩ min. 500V DC					
	Voltag	e proof		500V AC for 1minute				
	Tern stre	ninal ngth			5N for 1minute			
Mechanical performance	Actuator	Operating direction	50N	30N		50N		
	strength	Pulling direction	_	_		50N		
	Сс	old	-40℃ 96h		-20°C	96h		
Environmental performance	Dry heat		85°C 96h					
	Damp	heat		40°C, 90 to 95%RH 96h				
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Note

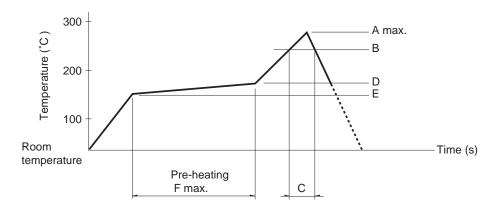
• Indicates applicability to all products in the series.

■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

Push Switches / Soldering Conditions

3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F (s)
SPEJ						
SPEF	260	230	40	180	150	120
SPEH						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.

 The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

■ Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SPPJ3, SPPJ2, SPUN, SPUJ, SPPH4, SPPH1	350±10℃	3+1/0s
SPED2, SPED4	350±10℃	3±0.5s
SPEJ	350±10°C	4s max.
SPEF	350±5℃	3s max.
SPEH	350℃ max.	3s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Ite	ms	Dip so	Idering
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s
SPUN	100℃ max.	60s max.	260±5℃	10±1s
SPUJ, SPPH4	_		260±5℃	5±1s
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_	_		10±1s

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Alps Alpine:

<u>SPUN190900</u> <u>SPUN191000</u> <u>SPUN191400</u> <u>SPUN191600</u> <u>SPUN192600</u> <u>SPUN192800</u> <u>SPUN192800</u> <u>SPUN194700</u> SPUN194900 <u>SPUN19C400</u>